

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kuo-Pin Yang	08/05/2011
Wei-Min Hsiao	08/09/2011
Cheng-Hui Hung	08/05/2011
RECEIVING PARTY DATA	
Name:	Advanced Semiconductor Engineering, Inc.
Street Address:	No. 26, Chin 3rd Road, Nantze Export Processing Zone,
City:	Kaohsiung City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13216063
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NAME OF SUBMITTER:	George D. Morgan
Total Attachments: 1 source=ASE2370Assignment#page1.tif	

OP \$40.00 13216063

ASSIGNMENT OF APPLICATION

WHEREAS, We,

Yang, Kuo-Pin, of No. 654, Sec. 3, Zhongzheng Rd., Meinong Dist., Kaohsiung City 843, Taiwan (R.O.C.) and a citizen of Taiwan R.O.C;

Hsiao, Wei-Min, of No. 8, Aly. 98, Ln. 638, Minzu 1st Rd., Sanmin Dist., Kaohsiung City 807, Taiwan (R.O.C.) a citizen of Taiwan R.O.C; and

Hung, Cheng-Hui, of No. 4, Ln 620, Minzu 1st Rd., Sanmin Dist., Kaohsiung City 807, Taiwan (R.O.C.) and a citizen of Taiwan R.O.C.

("Assignors"), have an interest in the invention entitled "**CARRIER BONDING AND DETACHING PROCESSES FOR A SEMICONDUCTOR WAFER**" which is the subject of a United States application for patent entitled above and in a Taiwan patent application filed on August 27, 2010, with serial number 099128960; and

WHEREAS, **Advanced Semiconductor Engineering, Inc.**, a corporation organized and existing under and by virtue of the laws of Taiwan R.O.C. with an address at No. 26, Chin 3rd Road, Nantze Export Processing Zone, Kaohsiung, Taiwan R.O.C. ("Assignee"), is desirous of acquiring Assignor's interest in the invention;

NOW THEREFORE, Assignor acknowledges receipt and adequacy of good and valuable consideration in exchange for this Assignment, and assigns to Assignee and its successors in interest, the full and exclusive right, title and interest to the invention described in the patent application listed above, in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, for the full term of the patent, including extensions of time, the same as if held by Assignor had this Assignment not been made.

Assignor covenants and agrees to cooperate with Assignee and execute all instruments or documents requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to the following: non-provisional utility, provisional, continuation, continuation-in-part, divisional, renewal or substitute, reissue, re-examination, or extension.

Assignor covenants and agrees to cooperate with Assignee in any litigation regarding the invention, patents or applications regarding the invention, including testifying for the benefit of Assignee.

Assignor covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Signed and Accepted by:

Yang Kuo Pin
Yang, Kuo-Pin

2011 / 8 / 5
Date

Hsiao, Wei Min
Hsiao, Wei-Min

2011 / 8 / 9
Date

Hung, Cheng Hui
Hung, Cheng-Hui

8/5/11
Date